Vishay Electro-Films



NiCr Thin Film, Top-Contact Resistor



Product may not be to scale

The SFN series resistor chips offer a combination of nichrome stability, good power rating and small size.

The SFNs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The SFNs are 100 % electrically tested and visually inspected to MIL-STD-883, method 2032, class H or class K.

FEATURES

- Wire bondable
- Chip size: 0.020" square
- Case: 0202
- Resistance range: 20 Ω to 510 k Ω
- Resistor material: Nichrome
- Oxidized silicon substrate
- 125 mW power
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

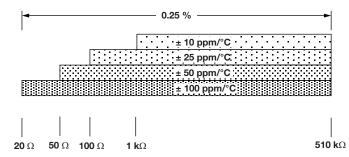
APPLICATIONS

Vishay EFI SFN resistor chips are widely used in hybrid packages where space is limited. Designed with capacity to handle substantial power loads, they also have the benefit of nichrome stability.

Recommended for hermetic environments where die is not exposed to moisture.

| TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES, AND TOLERANCES | | | | | |
|---|--------------------------------|--------|--|--|--|
| PARAMETER | VALUE | UNIT | | | |
| Total Resistance Range | 20 to 510K | Ω | | | |
| Standard Tolerances | ± 0.25 | % | | | |
| TCR | ± 10, ± 25, ± 50, ± 100, ± 250 | ppm/°C | | | |





| STANDARD ELECTRICAL SPECIFICATIONS | | | | | |
|--|-----------------------------------|------|--|--|--|
| PARAMETER | VALUE | UNIT | | | |
| Noise, MIL-STD-202, Method 308 100 Ω to 250 kΩ < 100 Ω or > 251 kΩ | -35 typ. -20 typ. | dB | | | |
| Stability, 1000 h, +125 °C, 50 mW | ± 0.25 max. ∆R/R | % | | | |
| Operating Temperature Range | -55 to +125 | °C | | | |
| Thermal Shock, MIL-STD-202, Method 107, Test Condition F | ± 0.25 max. ∆R/R | % | | | |
| High Temperature Exposure, +150 °C, 100 h | ± 0.5 max. $\Delta R/R$ | % | | | |
| Dielectric Voltage Breakdown | 200 | V | | | |
| Insulation Resistance | 10 ¹² min. | Ω | | | |
| Operating Voltage | 100 max. | V | | | |
| DC Power Rating at +70 °C (Derated to Zero at +175 °C) | 0.125 | W | | | |
| 5 x Rated Power Short-Time Overload, +25 °C, 5 s | ± 0.25 max. Δ <i>R</i> / <i>R</i> | % | | | |

Revision: 05-Jun-2023

Document Number: 61025



SFN

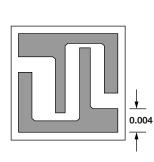
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishav.com/doc?91000

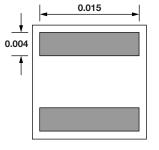
Vishay Electro-Films

DIMENSIONS in inches

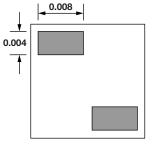
www.vishay.com

VISHAY

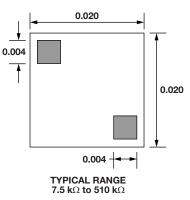




TYPICAL RANGE 20 Ω to 55 Ω



TYPICAL RANGE 56 Ω to 7.4 k Ω



SCHEMATIC

TYPICAL RANGE 20 Ω to 35 Ω

 $\bigcirc - & \bigcirc \bigcirc$

| MECHANICAL SPECIFICATIONS | | | | | |
|---------------------------|---|--|--|--|--|
| PARAMETER | VALUE | | | | |
| Chip Thickness | 0.010" ± 0.002" (0.254 mm ± 0.05 mm) | | | | |
| Chip Size | 0.020" x 0.020" ± 0.003" (0.51 mm x 0.51 mm ± 0.076 mm) | | | | |
| Chip Substrate Material | Oxidized silicon, 10 kÅ minimum SiO ₂ | | | | |
| Resistor Material | Nichrome (passivation optional) | | | | |
| Bonding Pad Size | 0.004" x 0.004" (0.10 mm x 0.10 mm) | | | | |
| Number of Pads | 2 | | | | |
| Pad Material | 15 kÅ minimum gold (Al optional) | | | | |
| Backing | None, lapped semiconductor silicon (Au back optional) | | | | |

| Global P | art Number: SFN50 | 000EKANHWS | | | | | | |
|----------------------------|---|---|--|--|--------------------------------|----------------------------------|-----------------|---|
| | | | | | | | | |
| Global P | art Number Descri | ption: SFN 5K | 1 % 100 ppm | Al None H | ws | | | |
| S | FN | 5 0 | 0 0 | 0 | FK | A N | н | WS |
| | | | | | | | <u> </u> | |
| MODEL | RESISTANCE | RESISTANCE MULTIPLIER CODE | TOLERANCE CODE (%) | TCR (ppm/°C) | TERMINATION | BACK METAL | VISUAL CLASS | PACKAGING CODE |
| SFN | First 4 digits are significant figures | B = 0.01 A = 0.1 | C = 0.25 D = 0.5 | $B = \pm 10$ $E = \pm 25$ | G = Au A = Al | G = Au N = none | | WS = waffle pack 100 min., 1 mult. |
| 20 x 20 size NiCr on | of resistance | 0 = 1 1 = 10 2 = 100 | F = 1.0 G = 2.0 J = 5.0 | $C = \pm 50$ $K = \pm 100$ $M = \pm 250$ | | | , | FW = full wafer |
| silicon | | 3 = 1000 | K = 10 | | | | | |



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

© 2025 VISHAY INTERTECHNOLOGY, INC. ALL RIGHTS RESERVED

Revision: 01-Jan-2025

1